ABSTRACT

A package structure, a semiconductor structure, and an electronic device are disclosed. The package structure includes: a base; a first pin array, disposed on the base, where the first pin array includes a plurality of first data pins; and a second pin array, disposed on the base, where the second pin array includes a plurality of second data pins. A blank region is disposed between the first pin array and the second pin array, the blank region extends from a center of the base to an edge of the base, an end part of the blank region is outside the first pin array, at least one of the first data pins and/or at least one of the second data pins are/is adjacent to the blank region, and a minimum dimension of the blank region is greater than a diameter of the first data pin.

[FIG. 5]